

Chu Yee Khor

List of Publications by Year in descending order

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Version: 2024-02-01

133
papers

1,466
citations

236925

25
h-index

414414

32
g-index

137
all docs

137
docs citations

137
times ranked

540
citing authors

#	ARTICLE	IF	CITATIONS
1	Effects of diamond nanoparticles reinforcement into lead-free Sn ^{3.0} Ag ^{0.5} Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials and Design</i> , 2015, 82, 206-215.	7.0	54
2	Three-dimensional numerical and experimental investigations on polymer rheology in meso-scale injection molding. <i>International Communications in Heat and Mass Transfer</i> , 2010, 37, 131-139.	5.6	48
3	Computational fluid dynamics modelling of human upper airway: A review. <i>Computer Methods and Programs in Biomedicine</i> , 2020, 196, 105627.	4.7	48
4	Thermo-mechanical challenges of reflowed lead-free solder joints in surface mount components: a review. <i>Soldering and Surface Mount Technology</i> , 2016, 28, 41-62.	1.5	47
5	Numerical and experimental investigations on effect of fan height on the performance of piezoelectric fan in microelectronic cooling. <i>International Communications in Heat and Mass Transfer</i> , 2009, 36, 51-58.	5.6	46
6	CFD modeling of pin shape effects on capillary flow during wave soldering. <i>International Journal of Heat and Mass Transfer</i> , 2014, 72, 400-410.	4.8	44
7	Experimental and numerical investigation of 3D gas flow temperature field in infrared heating reflow oven with circulating fan. <i>International Journal of Heat and Mass Transfer</i> , 2015, 87, 49-58.	4.8	43
8	FVM based numerical study on the effect of solder bump arrangement on capillary driven flip chip underfill process. <i>International Communications in Heat and Mass Transfer</i> , 2010, 37, 281-286.	5.6	42
9	Influence of pin offset in PCB through-hole during wave soldering process: CFD modeling approach. <i>International Communications in Heat and Mass Transfer</i> , 2013, 48, 116-123.	5.6	38
10	Optimization of the reflow soldering process with multiple quality characteristics in ball grid array packaging by using the grey-based Taguchi method. <i>Microelectronics International</i> , 2013, 30, 151-168.	0.6	37
11	Optimization of IC encapsulation considering fluid/structure interaction using response surface methodology. <i>Simulation Modelling Practice and Theory</i> , 2012, 29, 109-122.	3.8	35
12	Fluid-structure interaction analysis on the effect of chip stacking in a 3D integrated circuit package with through-silicon vias during plastic encapsulation. <i>Microelectronic Engineering</i> , 2014, 113, 40-49.	2.4	35
13	Finite volume based CFD simulation of pressurized flip-chip underfill encapsulation process. <i>Microelectronics Reliability</i> , 2010, 50, 98-105.	1.7	34
14	Investigation of the fluid/structure interaction phenomenon in IC packaging. <i>Microelectronics Reliability</i> , 2012, 52, 241-252.	1.7	33
15	Study on the fluid/structure interaction at different inlet pressures in molded packaging. <i>Microelectronic Engineering</i> , 2011, 88, 3182-3194.	2.4	32
16	Fluid/Structure Interaction Analysis of the Effects of Solder Bump Shapes and Input/Output Counts on Moulded Packaging. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012, 2, 604-616.	2.5	32
17	Influence of solder bump arrangements on molded IC encapsulation. <i>Microelectronics Reliability</i> , 2014, 54, 796-807.	1.7	32
18	Fluid/Structure Interaction Investigation in PBGA Packaging. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012, 2, 1786-1795.	2.5	31

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19	Effect of stacking chips and inlet positions on void formation in the encapsulation of 3D stacked flip-chip package. <i>International Communications in Heat and Mass Transfer</i> , 2012, 39, 670-680.	5.6	31
20	Numerical analysis on the effects of different inlet gates and gap heights in TQFP encapsulation process. <i>International Journal of Heat and Mass Transfer</i> , 2011, 54, 1861-1870.	4.8	30
21	Analysis of encapsulation process in 3D stacked chips with different microbump array. <i>International Communications in Heat and Mass Transfer</i> , 2012, 39, 1616-1623.	5.6	30
22	Application of flexible printed circuit board (FPCB) in personal computer motherboards: Focusing on mechanical performance. <i>Microelectronics Reliability</i> , 2012, 52, 744-756.	1.7	30
23	SAC TiO_2 nano-reinforced lead-free solder joint characterizations in ultra-fine package assembly. <i>Soldering and Surface Mount Technology</i> , 2018, 30, 1-13.	1.5	30
24	Effect of vertical stacking dies on flow behavior of epoxy molding compound during encapsulation of stacked-chip scale packages. <i>Heat and Mass Transfer</i> , 2010, 46, 1315-1325.	2.1	26
25	Analysis of fluid/structure interaction: Influence of silicon chip thickness in moulded packaging. <i>Microelectronics Reliability</i> , 2013, 53, 334-347.	1.7	26
26	Thermal Fluid-Structure Interaction in the Effects of Pin-Through-Hole Diameter during Wave Soldering. <i>Advances in Mechanical Engineering</i> , 2014, 6, 275735.	1.6	25
27	Optimization of flexible printed circuit board electronics in the flow environment using response surface methodology. <i>Microelectronics Reliability</i> , 2013, 53, 1996-2004.	1.7	22
28	Analytical Hierarchy Process for Natural Fiber Composites Automotive Armrest Thermoset Matrix Selection. <i>MATEC Web of Conferences</i> , 2017, 97, 01039.	0.2	21
29	Influence of PTH offset angle in wave soldering with thermal-coupling method. <i>Soldering and Surface Mount Technology</i> , 2014, 26, 97-109.	1.5	17
30	Numerical investigations on the effects of different cooling periods in reflow-soldering process. <i>Heat and Mass Transfer</i> , 2015, 51, 1413-1423.	2.1	17
31	Optimization of pin through hole connector in thermal fluid-structure interaction analysis of wave soldering process using response surface methodology. <i>Simulation Modelling Practice and Theory</i> , 2015, 57, 45-57.	3.8	16
32	Effect of zinc addition on the performance of aluminium alloy sacrificial anode for marine application. <i>AIP Conference Proceedings</i> , 2017, , .	0.4	16
33	A review of fluid-structure interaction simulation for patients with sleep related breathing disorders with obstructive sleep. <i>Computer Methods and Programs in Biomedicine</i> , 2019, 180, 105036.	4.7	16
34	Recent fluid-structure interaction modeling challenges in IC encapsulation – A review. <i>Microelectronics Reliability</i> , 2014, 54, 1511-1526.	1.7	15
35	Influence of Gap Height in Flip Chip Underfill Process With Non-Newtonian Flow Between Two Parallel Plates. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2012, 134, .	1.8	14
36	The influence of Fe ₂ O ₃ nano-reinforced SAC lead-free solder in the ultra-fine electronics assembly. <i>International Journal of Advanced Manufacturing Technology</i> , 2018, 96, 717-733.	3.0	14

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37	Characterization of SAC $\hat{\epsilon}$ x NiO nano-reinforced lead-free solder joint in an ultra-fine package assembly. Soldering and Surface Mount Technology, 2019, 31, 109-124.	1.5	14
38	Antioxidant Capacity and Total Phenolic Content of Fresh, Oven-Dried and Stir-Fried Tamarind Leaves. Current Research in Nutrition and Food Science, 2017, 5, 282-287.	0.8	14
39	Underfill process for two parallel plates and flip chip packaging. International Communications in Heat and Mass Transfer, 2012, 39, 1205-1212.	5.6	13
40	Finite volume-based simulation of the wave soldering process: Influence of the conveyor angle on pin-through-hole capillary flow. Numerical Heat Transfer; Part A: Applications, 2016, 69, 295-310.	2.1	13
41	Conceptual Design of Automotive Compressor for Integrated Portable Air Conditioning System. MATEC Web of Conferences, 2017, 97, 01040.	0.2	13
42	Influence of solder joint length to the mechanical aspect during the thermal stress analysis. AIP Conference Proceedings, 2017, , .	0.4	13
43	The Influence of Spiral Blade Distributor on Pressure Drop in a Swirling Fluidized Bed. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012106.	0.6	13
44	Thermal fluid-structure interaction of PCB configurations during the wave soldering process. Soldering and Surface Mount Technology, 2015, 27, 31-44.	1.5	12
45	Manufacturing Process Selection of Composite Bicycle TM s Crank Arm using Analytical Hierarchy Process (AHP). IOP Conference Series: Materials Science and Engineering, 2018, 318, 012058.	0.6	12
46	Simulation-Based Optimization of Plastic Injection Molding Parameter for Aircraft Part Fabrication Using Response Surface Methodology (RSM). IOP Conference Series: Materials Science and Engineering, 2019, 551, 012108.	0.6	12
47	Study on the Fluid $\hat{\epsilon}$ Structure Interaction of Flexible Printed Circuit Board Electronics in the Flow Environment. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1335-1345.	2.5	11
48	Numerical Investigation on the Effect of Pressure and Temperature on the Melt Filling During Injection Molding Process. Arabian Journal for Science and Engineering, 2016, 41, 1907-1919.	1.1	10
49	Biomechanical evaluation of different abutment-implant connections $\hat{\epsilon}$ A nonlinear finite element analysis. AIP Conference Proceedings, 2017, , .	0.4	10
50	Reflow Optimization Process: Thermal Stress Using Numerical Analysis and Intermetallic Spallation in Backwards Compatibility Solder Joints. Arabian Journal for Science and Engineering, 2015, 40, 1669-1679.	1.1	9
51	Plastic Ball Grid Array Encapsulation Process Simulation on Rheology Effect. Telkomnika (Telecommunication Computing Electronics and Control), 2011, 9, 27.	0.8	9
52	Effects of Blade Number on the Centrifugal Pump Performance: A Review. Arabian Journal for Science and Engineering, 2022, 47, 7945-7961.	3.0	9
53	Influence of Material Properties on the Fluid-Structure Interaction aspects during Molded Underfill Process. MATEC Web of Conferences, 2017, 97, 01059.	0.2	8
54	Heat transfer enhancement by flexible printed circuit board's deformation. International Communications in Heat and Mass Transfer, 2017, 84, 86-93.	5.6	7

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55	New approach for quality control in manufacturing process. AIP Conference Proceedings, 2017, , .	0.4	7
56	Study on the fluid-structure interaction of flexible printed circuit board motherboard in personal computer casings. Microelectronics International, 2013, 30, 138-150.	0.6	6
57	Numerical Modeling and Analysis of Microbump Pitch Effect in 3D IC Package with TSV During Molded Underfill (MUF). Engineering Applications of Computational Fluid Mechanics, 2013, 7, 210-222.	3.1	6
58	Effects of Solder Temperature on Pin Through-Hole during Wave Soldering: Thermal-Fluid Structure Interaction Analysis. Scientific World Journal, The, 2014, 2014, 1-13.	2.1	6
59	Antioxidant and Total Phenolic Content of Breadfruit (<i>Artocarpus altalis</i>) Leaves. MATEC Web of Conferences, 2018, 150, 06007.	0.2	6
60	Simulation based optimization of injection molding parameter for meso-scale product of dental component fabrication using response surface methodology (RSM). AIP Conference Proceedings, 2018, , .	0.4	6
61	A novel analytical filling time chart for design optimization of flip-chip underfill encapsulation process. International Journal of Advanced Manufacturing Technology, 2019, 105, 3521-3530.	3.0	6
62	Effects of Temperature on the Wave Soldering of Printed Circuit Boards: CFD Modeling Approach. Journal of Applied Fluid Mechanics, 2016, 9, 2053-2062.	0.2	6
63	Influence of printed circuit board thickness in wave soldering. Scientia Iranica, 2017, .	0.4	6
64	Effect of piezoelectric fan height on flow and heat transfer for electronics cooling applications. , 2008, , .		5
65	Visualization of Fluid/Structure Interaction in IC Encapsulation. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1239-1246.	2.5	5
66	Implications of Adjustable Fountain Wave in Pin Through Hole Soldering Process. Arabian Journal for Science and Engineering, 2014, 39, 9101-9111.	1.1	5
67	Effects of PCB thickness on adjustable fountain wave soldering. Sadhana - Academy Proceedings in Engineering Sciences, 2015, 40, 2197-2220.	1.3	5
68	Simulation Based Optimization of Thin Wall Injection Molding Parameter Using Response Surface Methodology. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012193.	0.6	5
69	Backward Compatibility Solder Joint Formation at High Peak Reflow Temperature for Aerospace Applications. Arabian Journal for Science and Engineering, 2016, 41, 1813-1823.	1.1	4
70	The Effect of Freestream Flow Velocities on the Flexible Printed Circuit Board with Different BGA Package Arrangements. Arabian Journal for Science and Engineering, 2017, 42, 2075-2086.	3.0	4
71	The Effect of Multi-staged Swirling Fluidized Bed on Air Flow Distribution. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012194.	0.6	4
72	Numerical study on the effect of fin length variation on the thermal performance of a bus duct conductor. Numerical Heat Transfer; Part A: Applications, 2023, 83, 116-133.	2.1	4

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73	A computational fluid dynamics analysis of the wave soldering process. International Journal of Numerical Methods for Heat and Fluid Flow, 2015, 25, 1231-1247.	2.8	3
74	Vibration analysis on compact car shock absorber. Journal of Physics: Conference Series, 2017, 908, 012025.	0.4	3
75	Finite element study on the integrity of tool holder with integrated internal cooling channel. AIP Conference Proceedings, 2017, , .	0.4	3
76	Turning of aluminum alloy Al-6063 under dry and wet condition using CVD coated tool. AIP Conference Proceedings, 2018, , .	0.4	3
77	Mechanical aspects analysis of the cyclone gasifier design via finite element method. AIP Conference Proceedings, 2018, , .	0.4	3
78	The influence of surface roughness on material dislocation of microindentation using bonded interface technique. Tribology - Materials, Surfaces and Interfaces, 2019, 13, 191-196.	1.4	3
79	Effect of filling level and fillet profile on pin-through-hole solder joint. International Journal of Advanced Manufacturing Technology, 2019, 102, 1467-1485.	3.0	3
80	Optimization of flexible printed circuit board's cooling with air flow and thermal effects using response surface methodology. Microelectronics International, 2021, 38, 182-205.	0.6	3
81	Computational Fluid Dynamics (CFD) Simulation on Mixing in T-Shaped Micromixer. IOP Conference Series: Materials Science and Engineering, 2020, 932, 012006.	0.6	3
82	Three dimensional numerical prediction of epoxy flow during the underfill process in flip chip packaging. , 2012, , .		2
83	The effect of different dental implant thread profiles on bone stress distribution. AIP Conference Proceedings, 2018, , .	0.4	2
84	Observation on dynamic behavior of droplets evaporation after the end-of-injection of diesel spray. AIP Conference Proceedings, 2018, , .	0.4	2
85	The Effect of Temperature on Tin Whisker Growth under Mechanical Stress. Solid State Phenomena, 2018, 280, 194-199.	0.3	2
86	Effect of Solder Joint Width to the Mechanical Aspect in Thermal Stress Analysis. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012105.	0.6	2
87	Computational Analysis of Airflow in Upper Airway under Light and Heavy Breathing Conditions for a Realistic Patient Having Obstructive Sleep Apnea. CMES - Computer Modeling in Engineering and Sciences, 2021, 128, 583-604.	1.1	2
88	Minimizing Warpage and Shrinkage of Plastic Car Rear Bumper Fabrication via Simulation Based Optimisation. Journal of Physics: Conference Series, 2021, 2051, 012012.	0.4	2
89	Effect of stacking chips and fluid/structure interaction simulation in 3D stacked flip-chip encapsulation process. , 2012, , .		1
90	Numerical Investigation on the Effect of Injection Pressure on Melt Front Pressure and Velocity Drop. Applied Mechanics and Materials, 0, 786, 210-214.	0.2	1

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91	Optimization of PBCA encapsulation considering fluid/structure interaction using response surface methodology. , 2016, , .		1
92	The effect of hydrophilicity of graphene oxide as additive towards performance of polysulfone membrane. AIP Conference Proceedings, 2017, , .	0.4	1
93	The effect of silica toward polymer membrane for water separation process. AIP Conference Proceedings, 2017, , .	0.4	1
94	Turbulent coolant inside cutting tool to control heat transfer during cutting process. AIP Conference Proceedings, 2018, , .	0.4	1
95	The effect of rotary tiller blade design on soil pulverization. AIP Conference Proceedings, 2018, , .	0.4	1
96	Numerical Investigation on the Effect of Squeegee Angle during Stencil Printing Process. Journal of Physics: Conference Series, 2018, 1082, 012057.	0.4	1
97	Influence of surface mount solder joint height during the thermo-mechanical analysis. AIP Conference Proceedings, 2018, , .	0.4	1
98	Moisture sorption behavior of Orthosiphon stamineus ground powder during storage. AIP Conference Proceedings, 2018, , .	0.4	1
99	The Effects of Oxidation Layer, Temperature, and Stress on Tin Whisker Growth: A Short Review. IOP Conference Series: Materials Science and Engineering, 2018, 318, 012063.	0.6	1
100	Investigation on the Mechanical Properties of Banana Trunk Fibreâ€“Reinforced Polymer Composites for Furniture Making Application. IOP Conference Series: Materials Science and Engineering, 2019, 551, 012107.	0.6	1
101	Numerical Simulation of Biodiesel Synthesis in T- Channel Microreactor. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012191.	0.6	1
102	Simulation Analysis of The Thickness Effect Towards Mechanical Aspects in The Design of Centrifugal Pump Casing. IOP Conference Series: Materials Science and Engineering, 2020, 864, 012192.	0.6	1
103	Heat transfer and deformation analysis of flexible printed circuit board under thermal and flow effects. Circuit World, 2021, 47, 213-221.	0.9	1
104	Simulation Based Optimization of Shrinkage in Injection Molding Process for Lamp Holder via Taguchi Method. Lecture Notes in Mechanical Engineering, 2021, , 319-329.	0.4	1
105	Fluid Structure Interaction Numerical Simulation of Wiresweep in Electronics Packaging. Telkomnika (Telecommunication Computing Electronics and Control), 2016, 14, 262.	0.8	1
106	Effect of heat sink design on the thermal characteristic in computational fluid dynamics analysis. IOP Conference Series: Materials Science and Engineering, 0, 932, 012106.	0.6	1
107	Simulation-based optimization of plastic injection molding parameters for mini centrifugal pump body using response surface methodology. IOP Conference Series: Materials Science and Engineering, 0, 932, 012111.	0.6	1
108	Computational fluid dynamics (CFD) simulation on mixing in Y-shaped micromixer. AIP Conference Proceedings, 2020, , .	0.4	1

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109	Simulation Study on the Production of Nano-Sized Materials at Mixing Stage. <i>Advanced Materials Research</i> , 0, 832, 118-123.	0.3	0
110	Performance studies of polysulfone-based membrane: Effect of silver acetate morphology. <i>AIP Conference Proceedings</i> , 2018, , .	0.4	0
111	An Experimental Investigation of Humidity Effect on fabrication of Green Ceramic Membrane Prepared Via Dry Phase Inversion. <i>IOP Conference Series: Materials Science and Engineering</i> , 2019, 551, 012103.	0.6	0
112	Design and Development of Tape Applicator For Managing Wire Purposes. <i>IOP Conference Series: Materials Science and Engineering</i> , 2019, 551, 012102.	0.6	0
113	Mechanical Design and Evaluation of Kapok Fibre Seeds Separator. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 864, 012190.	0.6	0
114	A Novel Green Technology Kaffir Lime Extract as Lizard Repellent. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 743, 012010.	0.6	0
115	Experimental and computational evaluations of the mechanical stresses of banana trunk fibre-reinforced epoxy resin composite in coffee table application. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 743, 012009.	0.6	0
116	The Effect of Different Khaya Senegalensis Raw Feedstock Particle Sizes On Solid Fuel Pellet Quality. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 864, 012101.	0.6	0
117	Influence of Different Materials on the Mechanical Aspects in the Design of Cyclone Gasifier. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 743, 012008.	0.6	0
118	Simulation-Based Optimization of Plastic Injection Molding Parameter for Automotive Car Wheel Fabrication Using Response Surface Methodology (RSM). <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 743, 012011.	0.6	0
119	The modified phase inversion and sintering technique for fabrication of ceramic membrane: Influence of kaolin composition and drying temperature. <i>AIP Conference Proceedings</i> , 2021, , .	0.4	0
120	Mechanical Design and Analysis of Safety Medical Syringe for Needlestick Injury Prevention. <i>Lecture Notes in Mechanical Engineering</i> , 2021, , 691-702.	0.4	0
121	Optimisation of Process Parameters in Plastic Injection Moulding Simulation for Blower Impeller™s Fan Using Response Surface Methodology. <i>Lecture Notes in Mechanical Engineering</i> , 2021, , 309-318.	0.4	0
122	Computation Fluid Dynamics Simulation of Airflow Ventilation System in 3D Indoor Mushroom Cultivation House Model. <i>Lecture Notes in Mechanical Engineering</i> , 2021, , 721-728.	0.4	0
123	A Short Review on Multi-stage Application in Fluidization Systems. <i>Lecture Notes in Mechanical Engineering</i> , 2021, , 713-720.	0.4	0
124	Numerical Simulation of Transesterification Reaction in Y-Shaped Microreactor. <i>Lecture Notes in Mechanical Engineering</i> , 2021, , 1281-1286.	0.4	0
125	The modified phase inversion and sintering technique for fabrication of ceramic membrane: Influence of Kaolin composition and drying temperature. <i>AIP Conference Proceedings</i> , 2021, , .	0.4	0
126	Conceptual Design Selection of Motorcycle Handle Brake Lever Component by TRIZ and Simulation. <i>Lecture Notes in Mechanical Engineering</i> , 2021, , 1245-1256.	0.4	0

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127	A Simulation on Influence of Cooling at Rake Face to Tool Temperature. Journal of Physics: Conference Series, 2021, 2051, 012052.	0.4	0
128	Influence of inlet velocity and heat flux on the thermal characteristic of various heat sink designs using CFD analysis. Journal of Physics: Conference Series, 2021, 2051, 012013.	0.4	0
129	Grid sensitivity studies for validation of human upper airways. IOP Conference Series: Materials Science and Engineering, 0, 932, 012107.	0.6	0
130	Effect of twist blade distributor on velocity distribution in a swirling fluidized bed. IOP Conference Series: Materials Science and Engineering, 0, 932, 012113.	0.6	0
131	Biomechanical assessment of different surgical approaches of zygomatic implant placement on prosthesis stress. IOP Conference Series: Materials Science and Engineering, 0, 932, 012108.	0.6	0
132	Thermo-mechanical analysis of various solder materials via finite element method. AIP Conference Proceedings, 2020, , .	0.4	0
133	Mechanical design and evaluations of new corn peeler design produced via three-dimensional printing technique. AIP Conference Proceedings, 2020, , .	0.4	0